

CJ8810 Datasheet

N-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^e	Q _g (Typ.)			
	0.028 at V _{GS} = 4.5 V	6 ^a				
20	0.042 at V _{GS} = 2.5 V	6 ^a	8.8 nC			
	0.050 at V _{GS} = 1.8 V	5.6				

FEATURES

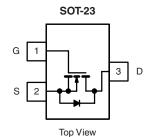
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- 100 % R_g Tested
- Compliant to RoHS Directive 2002/95/EC



ROHS COMPLIANT HALOGEN FREE

APPLICATIONS

- DC/DC Converters
- Load Switch for Portable Applications



ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted				
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V_{DS}	20	V	
Gate-Source Voltage		V_{GS}	± 12	v
	T _C = 25 °C		6 ^a	
Continuous Drain Current /T 150 °C\	T _C = 70 °C	I _D	5.1	
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C		5 ^{b, c}	
	T _A = 70 °C		4 ^{b, c}	A
Pulsed Drain Current		I _{DM}	20	
Continuous Source-Drain Diode Current	T _C = 25 °C		1.75	
Continuous Source-Diam Diode Current	T _A = 25 °C	l _S	1.04 ^{b, c}	
	T _C = 25 °C		2.1	
Maximum Power Dissipation	T _C = 70 °C	Ь	1.3	w
Maximum Fower Dissipation	T _A = 25 °C	P _D	1.25 ^{b, c}	VV
	T _A = 70 °C]	0.8 ^{b, c}	
Operating Junction and Storage Temperature	e Range	T _J , T _{stg}	- 55 to 150	°C
Soldering Recommendations (Peak Tempera	ature)	Ĭ	260	

THERMAL RESISTANCE RATINGS							
Parameter	Symbol	Typical	Maximum	Unit			
Maximum Junction-to-Ambient ^{b, d}	t ≤ 5 s	R _{thJA}	80	100	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	40	60] 5/**		

Notes:

- a. Package limited
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 5 s
- d. Maximum under steady state conditions is 125 $^{\circ}\text{C/W}.$
- e. Based on T_C = 25 °C.

服务热线:400-655-8788

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static	- Symbol	rest conditions	IVIII.	Typ.	WIGA.	Oilit
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA	20			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$			25		mV/°C
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 2.6		
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_{D} = 250 \mu A$	0.45		1.0	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V, } V_{GS} = \pm 8 \text{ V}$			± 100	nA
<u> </u>		V _{DS} = 20 V, V _{GS} = 0 V			1	_
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 20 V, V _{GS} = 0 V, T _J = 70 °C			10	μΑ
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	20			Α
	(*)	$V_{GS} = 4.5 \text{ V}, I_D = 5.0 \text{ A}$		0.028		
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 2.5 V, I _D = 4.7 A		0.042		Ω
	= = (=,	V _{GS} = 1.8 V, I _D = 4.3 A		0.050		
Forward Transconductance ^a	9 _{fs}	V _{DS} = 10 V, I _D = 5.0 A		24		S
Dynamic ^b					l	
Input Capacitance	C _{iss}			865		
Output Capacitance	C _{oss}	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		105		pF
Reverse Transfer Capacitance	C _{rss}			55		
·		$V_{DS} = 10 \text{ V}, V_{GS} = 5 \text{ V}, I_{D} = 5.0 \text{ A}$		12	18	18
Total Gate Charge	Q_g	20 / 00 / 0		8.8	14	_
Gate-Source Charge	Q _{gs}	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 5.0 \text{ A}$		1.1		nC
Gate-Drain Charge	Q _{gd}	50 / GO / D		0.7		
Gate Resistance	R _g	f = 1 MHz	0.5	2.4	4.8	Ω
Turn-On Delay Time	t _{d(on)}			8	16	
Rise Time	t _r	V_{DD} = 10 V, R_L = 2.2 Ω		17	26	
Turn-Off Delay Time	t _{d(off)}	$\text{I}_\text{D}\cong \text{4 A, V}_\text{GEN}=\text{4.5 V, R}_\text{g}=\text{1}~\Omega$		31	47	
Fall Time	t _f			8	16	ns
Turn-On Delay Time	t _{d(on)}			5	10	115
Rise Time	t _r	V_{DD} = 10 V, R_L = 2.2 Ω		13	20	=
Turn-Off Delay Time	t _{d(off)}	$I_D\cong 4$ A, $V_{GEN}=5$ V, $R_g=1$ Ω		21	32	
Fall Time	t _f			6	12	
Drain-Source Body Diode Characteristic	:S		<u>I</u>		l	
Continuous Source-Drain Diode Current	Is	T _C = 25 °C			1.75	
Pulse Diode Forward Current	I _{SM}				20	A
Body Diode Voltage	V_{SD}	I _S = 4 A, V _{GS} = 0 V		0.75	1.2	V
Body Diode Reverse Recovery Time	t _{rr}			12	20	ns
Body Diode Reverse Recovery Charge	Q _{rr}	I 4.4 dl/dt 100.4/::- T 05.00		5	10	nC
Reverse Recovery Fall Time	e Recovery Fall Time t_a			7		
Reverse Recovery Rise Time				5		ns

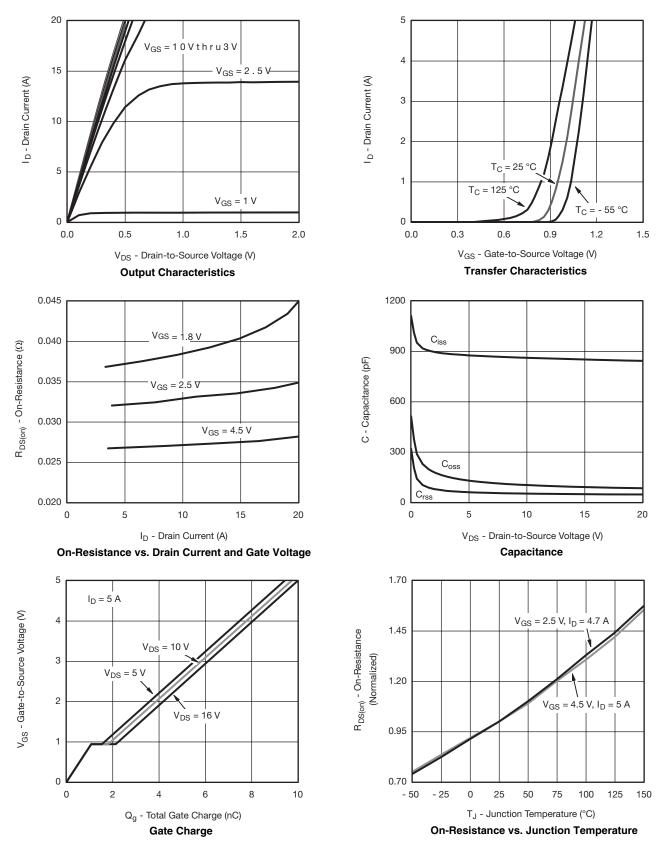
Notes:

- a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 % b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

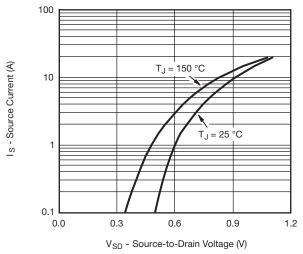


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

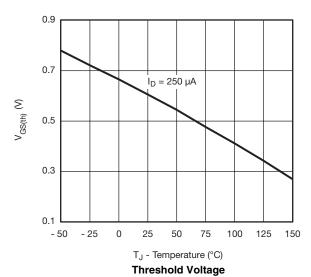




TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Source-Drain Diode Forward Voltage

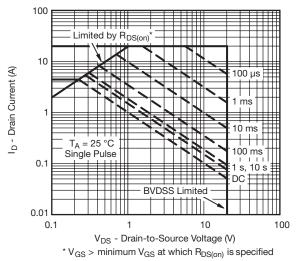


 $I_D = 5 \text{ A}$ I_D

On-Resistance vs. Gate-to-Source Voltage



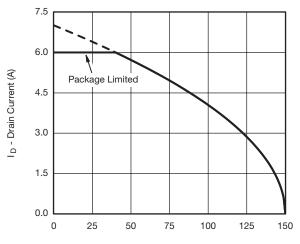
Single Pulse Power (Junction-to-Ambient)



Safe Operating Area, Junction-to-Ambient

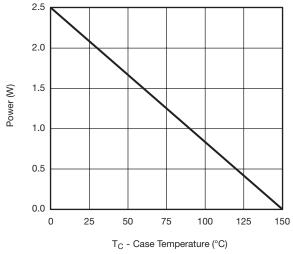


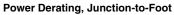
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

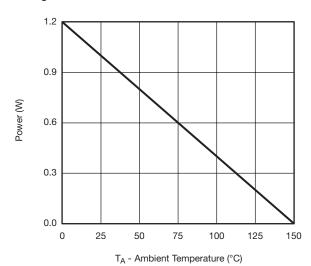


T_C - Case Temperature (°C)

Current Derating*







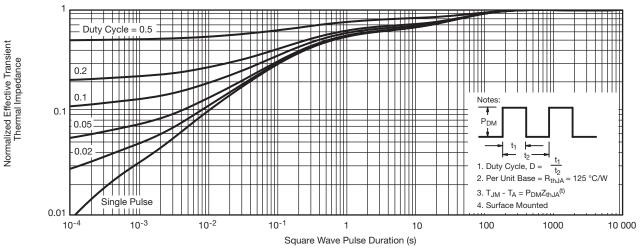
Power Derating, Junction-to-Ambient

^{*} The power dissipation P_D is based on $T_{J(max.)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

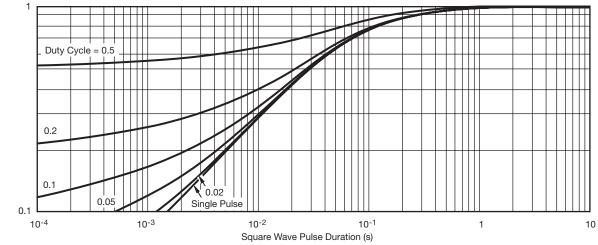
Normalized Effective Transient Thermal Impedance



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



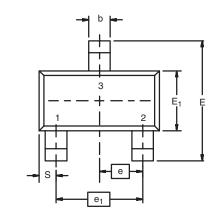
Normalized Thermal Transient Impedance, Junction-to-Ambient

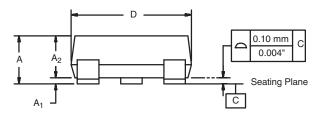


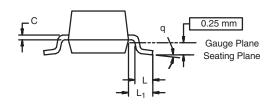
Normalized Thermal Transient Impedance, Junction-to-Foot



SOT-23 (TO-236): 3-LEAD





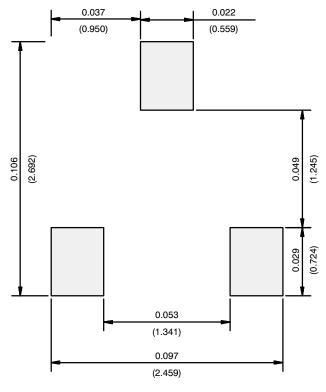


Dim -	MILLIM	IETERS	INCHES		
	Min	Max	Min	Max	
Α	0.89	1.12	0.035	0.044	
A ₁	0.01	0.10	0.0004	0.004	
A ₂	0.88	1.02	0.0346	0.040	
b	0.35	0.50	0.014	0.020	
С	0.085	0.18	0.003	0.007	
D	2.80	3.04	0.110	0.120	
E	2.10	2.64	0.083	0.104	
E ₁	1.20	1.40	0.047	0.055	
е	0.95 BSC		0.0374 Ref		
e ₁	1.90 BSC		0.0748 Ref		
L	0.40	0.60	0.016	0.024	
L ₁	0.64 Ref		0.025 Ref		
S	0.50 Ref		0.020 Ref		
q	3°	8°	3°	8°	
ECN: S-03946-Rev. K. 09-	Jul-01	•	<u> </u>		

DWG: 5479



RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads Dimensions in Inches/(mm)



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